



Features

- ESD Protection for 1 Line with Bi-directional.
- Provide ESD protection for the protected line to IEC 61000-4-2 (ESD) $\pm 20\text{kV}$ (air), $\pm 15\text{kV}$ (contact) IEC 61000-4-4 (EFT) 50A (5/50ns) Cable Discharge Event (CDE)
- Ultra-small SOD-523 package saves board space.
- Protect one I/O line or one power line
- Fast turn-on and Low clamping voltage
- For low operating voltage applications: 5V maximum
- Solid-state silicon-avalanche and active circuit triggering technology
- Green Part

Applications

- Computer Interfaces Protection
- Microprocessors Protection
- Serial and Parallel Ports Protection
- Control Signal Lines Protection
- Power lines on PCB Protection
- Latchup Protection

Description

AZ5125-01H is a design which includes a bi-directional ESD rated clamping cell to protect one power line, or one control line, or one low speed data line in an electronic systems. The AZ5125-01H has been specifically designed to protect sensitive components which are connected to power and control lines from over-voltage damage and latch-up caused by Electrostatic Discharging (ESD), Electrical Fast Transients (EFT), and Cable Discharge Event (CDE).

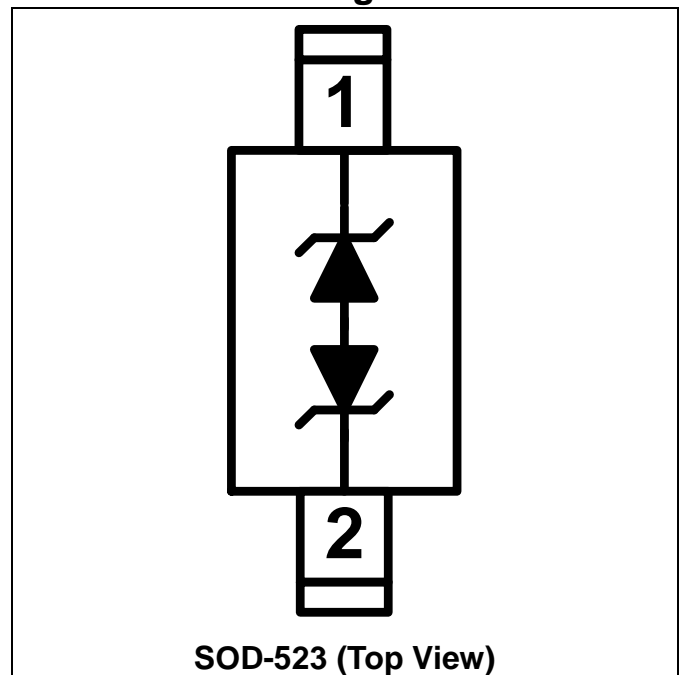
AZ5125-01H is a unique design which includes proprietary clamping cells in a single package.

During transient conditions, the proprietary clamping cells prevent over-voltage on the power line or control/data lines, protecting any downstream components.

AZ5125-01H is bi-directional and may be used on lines where the signal swings above and below ground.

AZ5125-01H may be used to meet the ESD immunity requirements of IEC 61000-4-2, Level 4 ($\pm 15\text{kV}$ air, $\pm 8\text{kV}$ contact discharge).

Circuit Diagram / Pin Configuration





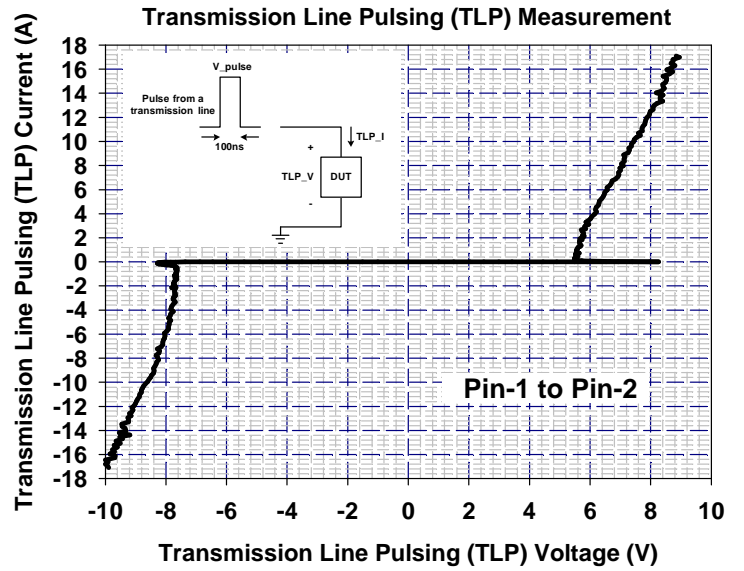
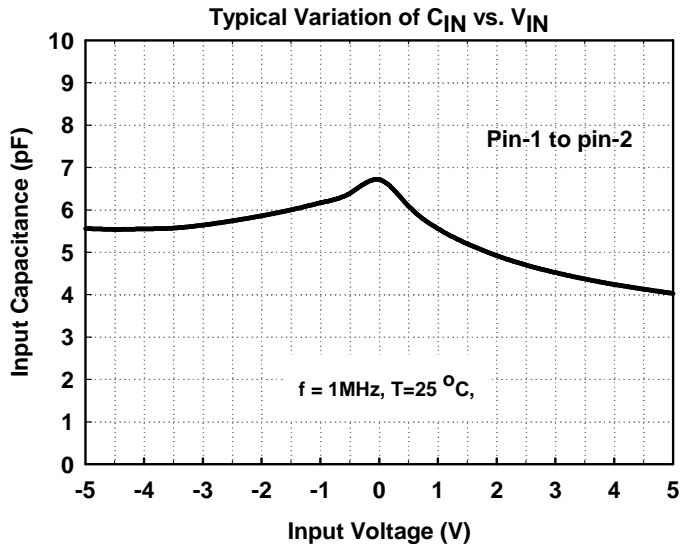
SPECIFICATIONS

| ABSOLUTE MAXIMUM RATINGS | | | |
|---------------------------------|-----------|---------------|-------------|
| PARAMETER | PARAMETER | RATING | UNITS |
| Operating Supply Voltage | V_{DC} | ± 6 | V |
| ESD per IEC 61000-4-2 (Air) | V_{ESD} | ± 20 | kV |
| ESD per IEC 61000-4-2 (Contact) | | ± 15 | |
| Lead Soldering Temperature | T_{SOL} | 260 (10 sec.) | $^{\circ}C$ |
| Operating Temperature | T_{OP} | -55 to +85 | $^{\circ}C$ |
| Storage Temperature | T_{STO} | -55 to +150 | $^{\circ}C$ |

| ELECTRICAL CHARACTERISTICS | | | | | | |
|----------------------------|---------------|---|------|-----|-----|---------|
| PARAMETER | SYMBOL | CONDITIONS | MINI | TYP | MAX | UNITS |
| Reverse Stand-Off Voltage | V_{RWM} | $T=25^{\circ}C$. | -5 | | 5 | V |
| Reverse Leakage Current | I_{Leak} | $V_{RWM} = \pm 5V, T=25^{\circ}C$. | | | 1 | μA |
| Reverse Breakdown Voltage | V_{BV} | $I_{BV} = 1mA, T=25^{\circ}C$. | 6 | | 9 | V |
| ESD Clamping Voltage | V_{ESD_CL} | IEC 61000-4-2 +6kV, $T=25^{\circ}C$, Contact mode. | | 10 | | V |
| Channel Input Capacitance | C_{IN} | $V_R = 0V, f = 1MHz, T=25^{\circ}C$. | | 7 | 9 | pF |



Typical Characteristics





Applications Information

The AZ5125-01H is designed to protect one line against System ESD/EFT/Cable-Discharge pulses by clamping them to an acceptable reference. It provides bi-directional protection.

The usage of the AZ5125-01H is shown in Fig. 1. Protected line, such as data lines, control lines, or power lines, is connected at pin 1. The pin 2 is connected to a ground plane on the board. Since AZ5125-01H is bi-directional, these connections can be reversed (protected line to pin 2, ground to pin 1). In order to minimize parasitic inductance in the board traces, all path lengths connected to the pins of AZ5125-01H should be kept as short as possible.

In order to obtain enough suppression of ESD induced transient, good circuit board is critical.

Thus, the following guidelines are recommended:

- Minimize the path length between the protected lines and the AZ5125-01H.
- Place the AZ5125-01H near the input terminals or connectors to restrict transient coupling.
- The ESD current return path to ground should be kept as short as possible.
- Use ground planes whenever possible.
- NEVER route critical signals near board edges and near the lines which the ESD transient easily injects to.

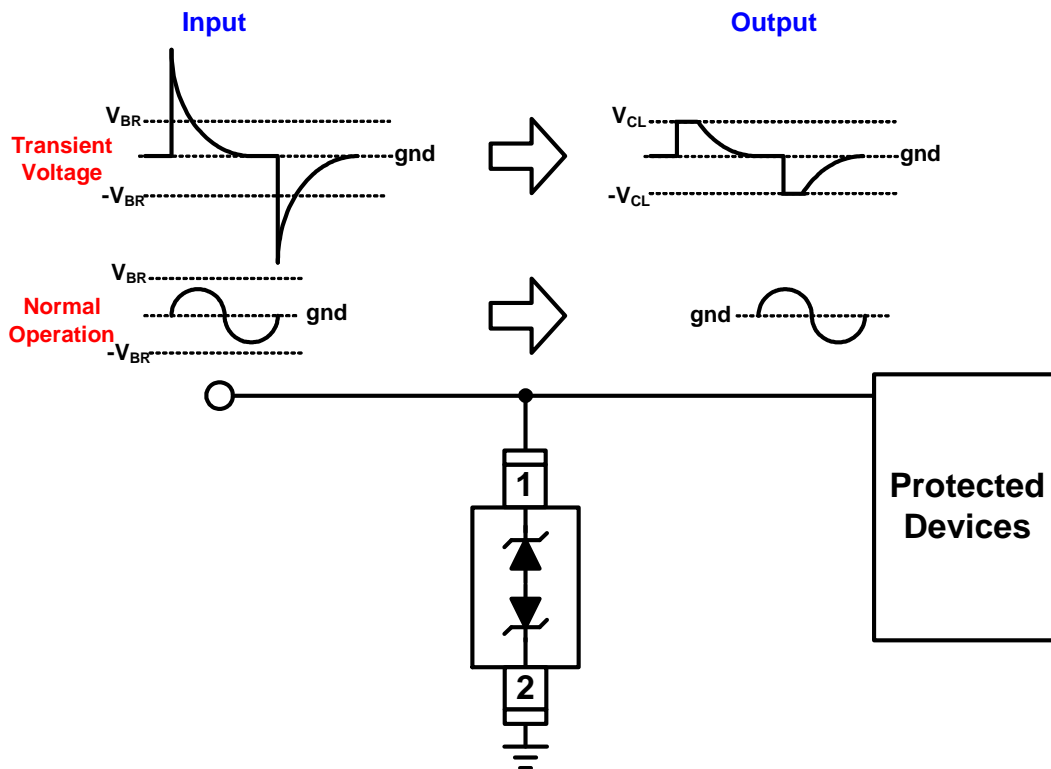
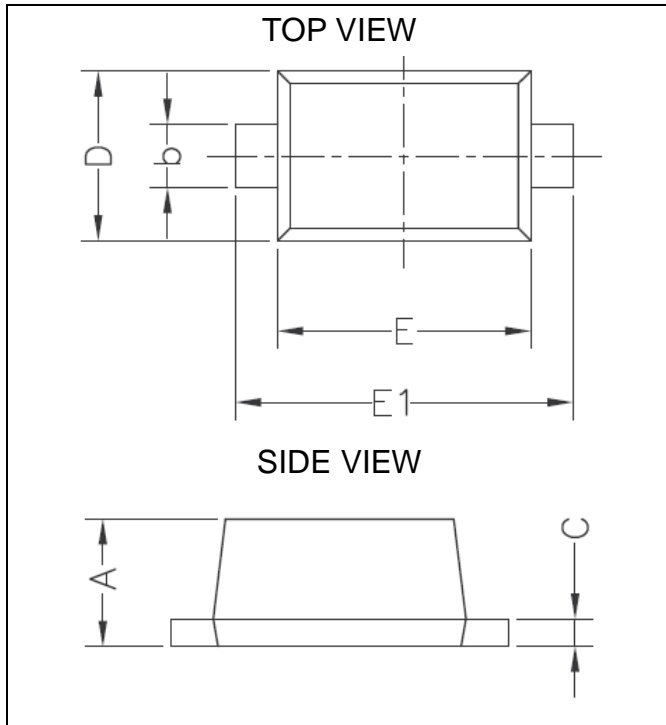


Fig. 1

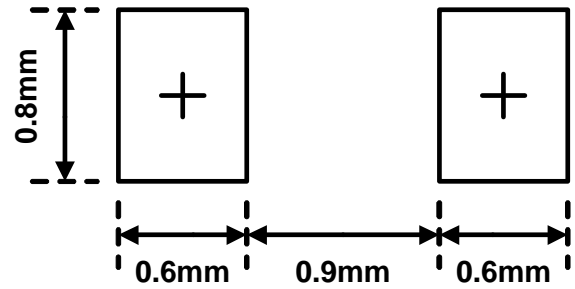
Mechanical Details

SOD-523

PACKAGE DIAGRAMS



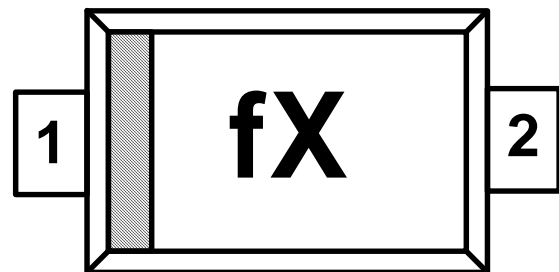
LAND LAYOUT



Notes:

This LAND LAYOUT is for reference purposes only. Please consult your manufacturing partners to ensure your company's PCB design guidelines are met.

MARKING CODE



f = Device Code
X = Date Code

PACKAGE DIMENSIONS

| Symbol | Millimeters | | Inches | |
|--------|-------------|-------|--------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| A | 0.5 | 0.715 | 0.020 | 0.028 |
| b | 0.25 | 0.35 | 0.010 | 0.014 |
| C | 0.08 | 0.2 | 0.003 | 0.008 |
| D | 0.7 | 0.9 | 0.028 | 0.035 |
| E | 1.1 | 1.3 | 0.043 | 0.051 |
| E1 | 1.5 | 1.7 | 0.059 | 0.067 |

| Part Number | Marking Code |
|-------------|--------------|
| AZ5125-01H | fX |

Ordering Information

| PN# | Material | Type | Reel size | MOQ/internal box | MOQ/carton |
|----------------|----------|------|-----------|-------------------|---------------------|
| AZ5125-01H.R7G | Green | T/R | 7 inch | 4 reel=12,000/box | 6 box=72,000/carton |



Revision History

| Revision | Modification Description |
|---------------------|--|
| Revision 2009/04/29 | Original and Formal Release. |
| Revision 2009/08/13 | Update the ESD clamping voltage. |
| Revision 2009/08/20 | Update the PACKAGE DIMENSIONS. |
| Revision 2011/07/28 | 1. Update the Company Logo. 2. Add the Ordering Information. |
| Revision 2012/04/03 | Modify the Circuit Diagram. |
| Revision 2012/04/25 | Update the level of ESD per IEC 61000-4-2 (Air) from 15KV to 20KV. |
| Revision 2013/01/08 | Update the PACKAGE DIMENSIONS. |